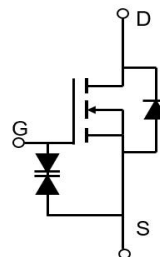


Description

Features

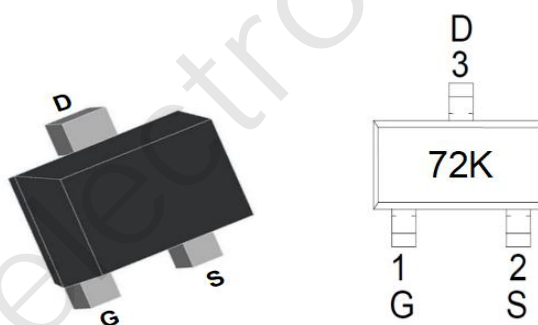
- 60V, 0.2A
- $R_{DS(ON)}$ Typ = 1.7 Ω @ $V_{GS} = 10V$
- $R_{DS(ON)}$ Typ = 2.0 Ω @ $V_{GS} = 4.5V$
- Advanced Trench Technology
- Excellent $R_{DS(ON)}$ and Low Gate Charge
- Lead Free
- ESD Protected: 2KV



Schematic Diagram

Application

- Load Switch
- PWM Application
- Power Management



Marking and Pin Assignment

Package Marking and Ordering Information

Device	Marking	Package	Outline	Reel Size	Reel (pcs)	Per Carton (pcs)
CRMLETL2N7002K	72K	SOT-723-3L	TAPING	7"	8000	320000

Absolute Maximum Ratings (@ $T_J = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Value	Units	
V _{DS}	Drain-to-Source Voltage	60	V	
V _{GS}	Gate-to-Source Voltage	±20	V	
I _D	Continuous Drain Current	T _A = 25°C	0.2	A
		T _A = 100°C	0.12	A
I _{DM}	Pulsed Drain Current ⁽¹⁾	0.8	A	
P _D	Power Dissipation	T _A = 25°C	0.15	W
R _{θJA}	Thermal Resistance, Junction to Ambient ⁽²⁾	850	°C/W	
T _J , T _{STG}	Junction & Storage Temperature Range	-55 to 150	°C	

Electrical Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
--------	-----------	------------	------	------	------	------

Off Characteristics

$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$I_D = 250\mu\text{A}$, $V_{GS} = 0\text{V}$	60	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 60\text{V}$, $V_{GS} = 0\text{V}$	-	-	1.0	μA
I_{GSS}	Gate-Body Leakage Current	$V_{DS} = 0\text{V}$, $V_{GS} = \pm 20\text{V}$	-	-	± 10	μA

On Characteristics

$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$, $I_D = 250\mu\text{A}$	1	1.6	2.0	V
$R_{DS(ON)}$	Static Drain-Source ON-Resistance ⁽³⁾	$V_{GS} = 10\text{V}$, $I_D = 0.1\text{A}$	-	1.7	2.1	Ω
		$V_{GS} = 4.5\text{V}$, $I_D = 0.1\text{A}$	-	2.0	2.4	Ω

Dynamic Characteristics

C_{iss}	Input Capacitance	$V_{GS} = 0\text{V}$, $V_{DS} = 25\text{V}$, $f = 1\text{MHz}$	-	28	-	pF
C_{oss}	Output Capacitance		-	11	-	pF
C_{rss}	Reverse Transfer Capacitance		-	4	-	pF
Q_g	Total Gate Charge	$V_{GS} = 0$ to 4.5V $V_{DS} = 10\text{V}$, $I_D = 0.2\text{A}$	-	1.7	-	nC
Q_{gs}	Gate Source Charge		-	0.3	-	nC
Q_{gd}	Gate Drain("Miller") Charge		-	0.6	-	nC

Switching Characteristics

$t_{d(on)}$	Turn-On DelayTime	$V_{GS} = 10\text{V}$, $V_{DD} = 10\text{V}$ $I_D = 0.2\text{A}$, $R_{GEN} = 10\Omega$	-	2	-	ns
t_r	Turn-On Rise Time		-	15	-	ns
$t_{d(off)}$	Turn-Off DelayTime		-	7	-	ns
t_f	Turn-Off Fall Time		-	20	-	ns

Drain-Source Diode Characteristics and Max Ratings

I_S	Maximum Continuous Drain to Source Diode Forward Current	$V_{GS} = 0\text{V}$, $I_S = 0.2\text{A}$	-	-	0.2	A
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	0.8	A
V_{SD}	Drain to Source Diode Forward Voltage		-	-	1.2	V

- Notes:
1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
 2. $R_{\theta JA}$ is measured with the device mounted on a 1inch² pad of 2oz copper FR4 PCB
 3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 0.5\%$.

Test Circuit

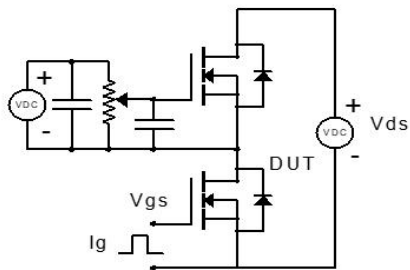


Figure 1: Gate Charge Test Circuit & Waveform

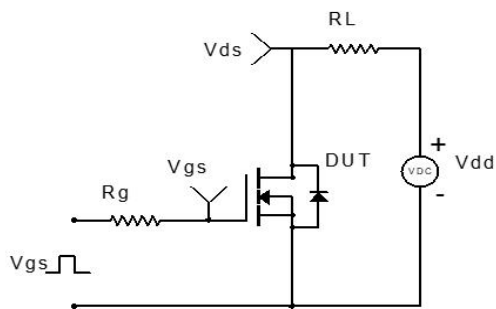


Figure 2: Resistive Switching Test Circuit & Waveform

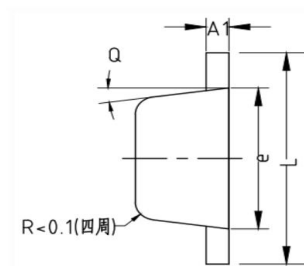
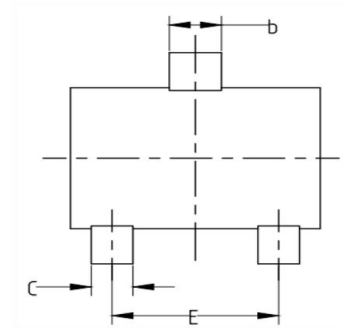
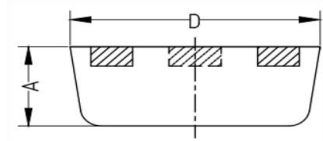


Figure 3: Unclamped Inductive Switching Test Circuit & Waveform



Figure 4: Diode Recovery Test Circuit & Waveform

Package Mechanical Data(SOT-723-3L)



COMMON DIMENSION (MM)			
PKG	SOT-723-3L		
SYMBOL	MIN	NOM	MAX
A	0.420	0.450	0.480
A1	0.100	0.110	0.120
b	0.230	0.250	0.280
c	0.180	0.200	0.235
D	1.150	1.200	1.300
E	0.750	0.800	0.850
L	1.170	1.200	1.240
e	0.750	0.800	0.850
Q		8°	

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